

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT6405619

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
HUNTEAK LEE	11/13/2020
KYUNGHWAN KIM	11/12/2020
HEESOO LEE	11/12/2020
CHANGOH KIM	11/13/2020
KYOUNGHEE PARK	11/13/2020
JINHEE JUNG	11/12/2020
OMIN KWON	11/12/2020
JIWON LEE	11/13/2020
YUJEONG JANG	11/12/2020
RECEIVING PARTY DATA	
Name:	STATS CHIPPAK PTE. LTD.
Street Address:	5 YISHUN STREET 23
City:	SINGAPORE
State/Country:	SINGAPORE
Postal Code:	768442
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	16950295
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	480-499-9400
Email:	main@plgaz.com
Correspondent Name:	PATENT LAW GROUP: ATKINS AND ASSOCIATES
Address Line 1:	123 W. CHANDLER HEIGHTS ROAD, #12535
Address Line 4:	CHANDLER, ARIZONA 85248
ATTORNEY DOCKET NUMBER:	2515.0527
NAME OF SUBMITTER:	LISA ROSSETTI

SIGNATURE:	/Lisa Rossetti/
DATE SIGNED:	11/17/2020
Total Attachments: 9 source=16950295ASSIGNMENT#page1.tif source=16950295ASSIGNMENT#page2.tif source=16950295ASSIGNMENT#page3.tif source=16950295ASSIGNMENT#page4.tif source=16950295ASSIGNMENT#page5.tif source=16950295ASSIGNMENT#page6.tif source=16950295ASSIGNMENT#page7.tif source=16950295ASSIGNMENT#page8.tif source=16950295ASSIGNMENT#page9.tif	

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HUNTEAK LEE of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SELECTIVE EMI SHIELDING USING PREFORMED MASK, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2915.0527, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

I hereby sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to application(s) for patent filed in all countries foreign to the United States, and in and to application(s) for patent filed under any and all international conventions and treaties, and in and to any patent issuing therefrom, which describe, illustrate, and claim the above-identified invention(s). I hereby also sell, assign, and transfer unto STATS ChipPAC, the entire right, title, and interest in and to all rights under any and all international conventions and treaties in respect of the above-identified invention(s). I authorize STATS ChipPAC to apply for patent in foreign countries directly in its own name, and to claim the priority of the filing date under the provisions of any and all domestic laws and international conventions and treaties.

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I agree that, when requested, I will, without charge to STATS ChipPAC, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the invention(s) in any and all countries and for vesting title thereto in STATS ChipPAC, its successors, assigns, and legal representatives or nominees.

I covenant with STATS ChipPAC, its successors, assigns, and legal representatives that the interest and property hereby conveyed is free from any prior assignment, grant, mortgage, license, or other encumbrance.

2020, 11, 13

Date Signed



Signature for HUNTEAK LEE

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYUNGHWAN KIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SELECTIVE EMI SHIELDING USING PREFORMED MASK, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0527, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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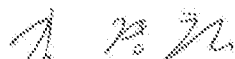
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2020.11.12

Date Signed



Signature for KYUNGHWAN KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, HEESOO LEE of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SELECTIVE EMI SHIELDING USING PREFORMED MASK, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0527, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

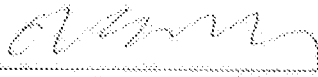
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11-12-2020
Date Signed


Signature for HEESOO LEE

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, CHANGOH KIM of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SELECTIVE EMI SHIELDING USING PREFORMED MASK, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0527, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

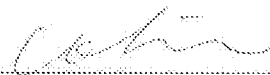
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2020-11-13
Date Signed


Signature for CHANGOH KIM

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, KYOUNGHEE PARK of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SELECTIVE EMI SHIELDING USING PREFORMED MASK, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0527, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

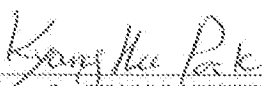
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2020-11-13
Date Signed


Signature for KYOUNGHEE PARK

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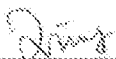
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Nov. 12th, 2006
Date Signed


Signature for JINHEE JUNG

ASSIGNMENT AND AGREEMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, I, OMIN KWON of Korea, have sold, assigned, and transferred, or do hereby sell, assign, and transfer unto STATS ChipPAC Pte. Ltd. (STATS ChipPAC), having its principal office at 5 Yishun Street 23, Singapore 768442, and its successors, assigns, and legal representatives, the entire right, title, and interest in and to certain invention(s) entitled SELECTIVE EMI SHIELDING USING PREFORMED MASK, which is described, illustrated, and/or claimed in an application for patent under Attorney Docket No. 2515.0527, together with the entire right, title and interest in and to the application, and in and to any continuation, division, reissue, reexamination, extension, renewal, or substitute thereof, and in and to any patent which may grant upon such application(s).

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Nov. 12th, 2000
Date Signed

Kwon
Signature for OMIN KWON

ASSIGNMENT AND AGREEMENT

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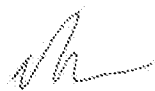
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2020-11-13
Date Signed


Signature for JIWON LEE

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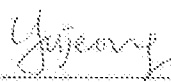
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Nov. 17th 2020
Date Signed


Signature for YUJEONG JANG